



PART NO. : TD04-2006QRL

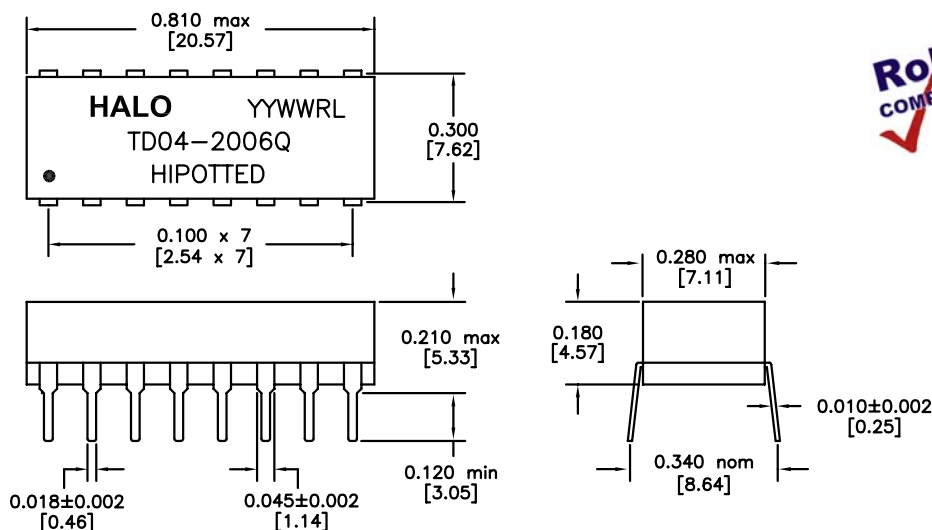
16PIN DIP ISOLATION MODULE
MEET REQUIREMENTS OF 10BASE-T
FILTERLESS SOLUTION

UL/EN60950 AND DEMKO RECOGNIZED
RoHS COMPLIANT

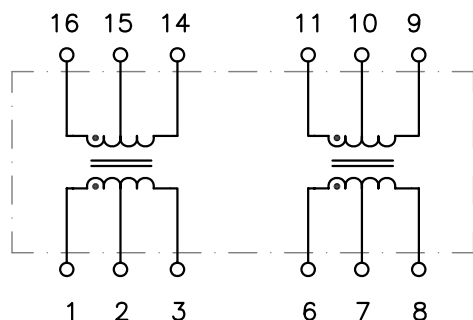
COMPATIBLE TO LEAD-FREE WAVE SOLDERING
PROCESS FOR THROUGH HOLE COMPONENTS
EXTENDED OPERATING TEMP. -40/+85°C

ELECTRICAL SPECIFICATIONS @25° C

TURNS RATIO
 P1-3:P16-14 1CT:1CT ±3%
 P6-8:P11-9 1CT:1CT ±3%
 OCL P1-3,P6-8 200µH typ
 DCR P1-3,P6-8 0.4Ω max
 Cw/w 15pF max
 LL P1-3,P6-8 0.3µH max
 ISOLATION 2000Vrms



DIMENSIONS: Inch [mm]
 TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

HALO/PBL CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE	TITLE	16PIN ISOLATION MODULE	SIGNATURES	DATE	REV.	DESC.	DATE
	FOR	10BASE-T	DRAWN	PETER LU	12/12/06	A	
	PART NO.	TD04-2006QRL	CHECKED	LEI KEONG	12/12/06		
	SCALE	NONE	APPROVED	PETER LU	12/12/06		
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